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REISSUE APPLICATION DECLARATION BY THE ASSIGNEEDocket Number (optional)
501.20289RC6

I hereby declare that:

My residence and post office address and citizenship are stated below next to my name.

I am authorized to act on behalf of the following assignee: HITACHI, LTD.and the title of my position with said assignee is: Executive Managing Director

The entire title to the patent identified below is vested in said assignee.

Name of Patentee(s):

Hisashi Maejima, Hiroshi Nishizuka, Susumu Komoriya and Etuo EgashiraPatent Number
5,230,747

Date of Patent Issued

July 27, 1993Title of Invention
WAFER HAVING CHAMFERED BEND PORTIONS IN THE JOINT REGIONS BETWEEN THE CONTOUR OF THE WAFER AND THE CUT-AWAY PORTION OF THE WAFER

I believe said patentee(s) to be the original, first and sole/joint inventor(s) of the subject matter which is described and claimed in said patent, for which a reissue patent is sought on the invention entitled WAFER HAVING CHAMFERED BEND PORTIONS IN THE JOINT REGIONS BETWEEN THE CONTOUR OF THE WAFER AND THE CUT-AWAY PORTION OF THE WAFER, the specification of which

is attached hereto.

was filed on _____ as reissue application number _____
and was amended on _____
(If applicable)

I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above.

Claim for priority - see page 3.
I acknowledge the duty to disclose information which is material to patentability as defined in 37 CFR 1.56.
An Information Disclaimer Statement is filed herewith.
I verily believe the original patent to be wholly or partly inoperative or invalid, for the reasons described below. (Check all boxes that apply.)

- by reason of a defective specification or drawing.
- by reason of the patentee claiming more or less than he had the right to claim in the patent.
- by reason of other errors.

At least one error upon which reissue is based is described as follows:

There is a mistake in the issued claims of the patent in that by a description of the issued claims, the purpose of providing a notch was unclear. The expression "curved notch" in claims 1 and 2 should be changed to -- curved positioning notch -- to clarify this and new claims 4-13 should be added. New claims 4-13 are not broadening the invention and were originally disclosed in the application, but applicant failed to notice the claiming in the application of U.S. Patent No. 5,230,747.

[Attach additional sheets, if needed.]

All errors corrected in this reissue application arose without any deceptive intention on the part of the applicant.

[Page 1 of 2]

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(REISSUE APPLICATION DECLARATION BY THE ASSIGNEE, page 2)

Docket Number (Optional)
501.20289RC6

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

| | |
|---------------------|--|
| Name(s) | Registration Number |
| Ronald J. Shore | 28,577 |
| Donald R. Antonelli | 20,296 |
| David T. Terry | 20,178 (and others on attached Addendum) |
| Melvin Kraus | 22,466 |

Correspondence Address: Direct all communications about the application to:

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020457

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| <input type="checkbox"/> Firm or Individual Name | | | |
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| Address | | | |
| City | State | | Zip |
| Country | | | |
| Telephone | Fax | | |

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine and imprisonment, or both, under 18 U.S.C. 1 001, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent to which this declaration is directed.

Full name of person signing (given name, family name)

Yasuo Sakuta

Signature

Date

Oct. 17, 2000

Address of Assignee Hitachi, Ltd., Intellectual Property Group, New Marunouchi Bldg., 5-1, Marunouti 1-chome, Chiyoda-ku, Tokyo 100-8220 Japan

| | |
|--|----------------------|
| Patentee Hisashi Maejima | Citizenship Japan |
| Residence/Post Office Address Residence: Tokyo, Japan Post Office Address: 2-188-2, Takagi, Higashiyamato-shi, Tokyo Japan | |
| Patentee Hiroshi Nishizuka | Citizenship Japan |
| Residence/Post Office Address Residence: Tokyo, Japan Post Office Address: 3-1-10-102, Takiyama, Higashikurume-shi, Tokyo Japan | |

| | |
|---|-----------------------------|
| Patentee Susumu Komoriya | Citizenship Japan |
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| Patentee Etuo Egashira | Citizenship Japan |
| Residence/Post Office Address Residence: Yamanashi, Japan Post Office Address: 2490-4, Nishiyahata, Ryuou-cho, Nakakoma-gun, Yamanashi, Japan | |

PRIORITY CLAIM

I hereby claim foreign priority benefits under Title 35, United States Code, section 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed.

Such applications have been filed as follows:

EARLIEST FOREIGN APPLICATION(S), IF ANY FILED WITHIN 12 MONTHS (6 MONTHS FOR DESIGN) PRIOR TO SAID APPLICATION

| Country | Application No. | Date of filing (day, month, year) | Date of issue (day, month, year) | Priority claimed |
|---------|-----------------|--------------------------------------|-------------------------------------|---------------------|
| Japan | 570131949 | 30 July 1982 | | Yes |
| | | | | |
| | | | | |

A D D E N D UPlease type a plus sign (+) inside this box →

PTO/SB/02C (3-97)

Approved for use through 9/30/98. OMB 0651-0032

Patent and Trademark Office; U.S. DEPARTMENT OF COMMERCE
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INFORMATION
(Supplemental Sheet)**

| Name | Registration Number | Name | Registration Number |
|---------------------|---------------------|------|---------------------|
| Frederick D. Bailey | 42,282 | | |
| Carl I. Brundidge | 29,621 | | |
| Hung H. Bui | 40,415 | | |
| James N. Dresser | 22,973 | | |
| Dale C. Hogue | 32,832 | | |
| Melvin Kraus | 22,466 | | |
| Gregory E. Montone | 28,141 | | |
| David C. Oren | 38,694 | | |
| Alan E. Schiavelli | 32,087 | | |
| Paul J. Skwierawski | 32,173 | | |
| William I. Solomon | 28,565 | | |
| George N. Stevens | 36,938 | | |
| Donald E. Stout | 26,422 | | |
| Noel B. Whitley | 27,477 | | |
| Henry M. Zykorie | | | |

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|--|--|--|-----------------------------------|--|---|--|--|-------------------------------------|
| REISSUE APPLICATION BY THE ASSIGNEE, OFFER TO SURRENDER PATENT | | Docket Number (Optional) 501.20289RC6 | | | | | | |
| <p>This is part of the application for a reissue patent based on the original patent identified below.</p> <p>Name of Patentee(s): Hisashi MAEJIMA, Hiroshi NISHIZUKA, Susumu KOMORIYA and Etuo EGASHIRA</p> <table border="1"> <tr> <td>Patent Number 5,230,747</td> <td>Date Patent Issued July 27, 1993</td> </tr> <tr> <td colspan="2">Title of Invention WAFER HAVING CHAMFERED BEND PORTIONS IN THE JOINT REGIONS BETWEEN THE CONTOUR OF THE WAFER AND THE CUT-AWAY PORTION OF THE WAFER</td> </tr> </table> <p>HITACHI, LTD. is the assignee of the entire interest in the original patent. The assignment is recorded at Reel 4900, Frame 958. I offer to surrender the original patent.</p> <p><input checked="" type="checkbox"/> A certificate under 37 CFR 3.73(b) is attached.</p> <p>I am authorized to act on behalf of the assignee.</p> <p>I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 18 U.S.C. 1001 and that such willful false statements may jeopardize the validity of the application, any patent issued thereon, or any patent to which this declaration is directed.</p> <p>Name of assignee HITACHI, LTD.</p> <table border="1"> <tr> <td>Signature of person signing for assignee <i>Yasuo Sakuta</i></td> <td>Date <i>Oct. 17, 2000</i></td> </tr> </table> <p>Typed or printed name and title of person signing for assignee Yasuo Sakuta, Executive Managing Director</p> | | | Patent Number 5,230,747 | Date Patent Issued July 27, 1993 | Title of Invention WAFER HAVING CHAMFERED BEND PORTIONS IN THE JOINT REGIONS BETWEEN THE CONTOUR OF THE WAFER AND THE CUT-AWAY PORTION OF THE WAFER | | Signature of person signing for assignee <i>Yasuo Sakuta</i> | Date <i>Oct. 17, 2000</i> |
| Patent Number 5,230,747 | Date Patent Issued July 27, 1993 | | | | | | | |
| Title of Invention WAFER HAVING CHAMFERED BEND PORTIONS IN THE JOINT REGIONS BETWEEN THE CONTOUR OF THE WAFER AND THE CUT-AWAY PORTION OF THE WAFER | | | | | | | | |
| Signature of person signing for assignee <i>Yasuo Sakuta</i> | Date <i>Oct. 17, 2000</i> | | | | | | | |

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